



Low switching losses  
Low reverse recovery charge  
Distributed amplified gate for high  $dI_T/dt$

**Fast Thyristor**  
**Type TFI573-2000-12**

Mean on-state current	I <sub>TAV</sub>	2000 A
Repetitive peak off-state voltage	V <sub>DRM</sub>	1000 ÷ 1200 V
Repetitive peak reverse voltage	V <sub>RRM</sub>	
Turn-off time	t <sub>q</sub>	10.0; 12.5; 16.0; 20.0 μs
V <sub>DRM</sub> , V <sub>RRM</sub> , V	1000	1200
Voltage code	10	12
T <sub>j</sub> , °C	– 60 ÷ 125	

**MAXIMUM ALLOWABLE RATINGS**

Symbols and parameters		Units	Values	Test conditions	
<b>ON-STATE</b>					
I <sub>TAV</sub>	Mean on-state current	A	2000 3825	T <sub>c</sub> =94 °C; Double side cooled; T <sub>c</sub> =55 °C; Double side cooled; 180° half-sine wave; 50 Hz	
I <sub>TRMS</sub>	RMS on-state current	A	3140	T <sub>c</sub> =94 °C; Double side cooled; 180° half-sine wave; 50 Hz	
I <sub>TSM</sub>	Surge on-state current	kA	52.0 60.0	T <sub>j</sub> =T <sub>j</sub> max T <sub>j</sub> =25 °C	180° half-sine wave; 50 Hz (t <sub>p</sub> =10 ms); single pulse; V <sub>D</sub> =V <sub>R</sub> =0 V; Gate pulse: I <sub>G</sub> =I <sub>FGM</sub> ; V <sub>G</sub> =20 V; t <sub>GP</sub> =50 μs; di <sub>G</sub> /dt=2 A/μs
			55.0 63.0	T <sub>j</sub> =T <sub>j</sub> max T <sub>j</sub> =25 °C	180° half-sine wave; 60 Hz (t <sub>p</sub> =8.3 ms); single pulse; V <sub>D</sub> =V <sub>R</sub> =0 V; Gate pulse: I <sub>G</sub> =I <sub>FGM</sub> ; V <sub>G</sub> =20 V; t <sub>GP</sub> =50 μs; di <sub>G</sub> /dt=2 A/μs
I <sup>2</sup> t	Safety factor	A <sup>2</sup> ·10 <sup>3</sup>	13520 18000	T <sub>j</sub> =T <sub>j</sub> max T <sub>j</sub> =25 °C	180° half-sine wave; 50 Hz (t <sub>p</sub> =10 ms); single pulse; V <sub>D</sub> =V <sub>R</sub> =0 V; Gate pulse: I <sub>G</sub> =I <sub>FGM</sub> ; V <sub>G</sub> =20 V; t <sub>GP</sub> =50 μs; di <sub>G</sub> /dt=2 A/μs
			12550 16470	T <sub>j</sub> =T <sub>j</sub> max T <sub>j</sub> =25 °C	180° half-sine wave; 60 Hz (t <sub>p</sub> =8.3 ms); single pulse; V <sub>D</sub> =V <sub>R</sub> =0 V; Gate pulse: I <sub>G</sub> =I <sub>FGM</sub> ; V <sub>G</sub> =20 V; t <sub>GP</sub> =50 μs; di <sub>G</sub> /dt=2 A/μs
<b>BLOCKING</b>					
V <sub>DRM</sub> , V <sub>RRM</sub>	Repetitive peak off-state and Repetitive peak reverse voltages	V	1000÷1200	T <sub>j min</sub> < T <sub>j</sub> <T <sub>j</sub> max; 180° half-sine wave; 50 Hz; Gate open	
V <sub>DSM</sub> , V <sub>RSM</sub>	Non-repetitive peak off-state and Non-repetitive peak reverse voltages	V	1100÷1300	T <sub>j min</sub> < T <sub>j</sub> <T <sub>j</sub> max; 180° half-sine wave; 50 Hz;single pulse; Gate open	
V <sub>D</sub> , V <sub>R</sub>	Direct off-state and Direct reverse voltages	V	0.75·V <sub>DRM</sub> 0.75·V <sub>RRM</sub>	T <sub>j</sub> =T <sub>j</sub> max; Gate open	

TRIGGERING				
$I_{FGM}$	Peak forward gate current	A	10	$T_j=T_{j \max}$
$V_{RGM}$	Peak reverse gate voltage	V	5	
$P_G$	Gate power dissipation	W	8	$T_j=T_{j \max}$ for DC gate current
SWITCHING				
$(di_T/dt)_{crit}$	Critical rate of rise of on-state current non-repetitive ( $f=1$ Hz)	A/ $\mu$ s	2500	$T_j=T_{j \max}$ ; $V_D=0.67V_{DRM}$ ; $I_{TM}=2I_{TAV}$ ; Gate pulse: $I_G=I_{FGM}$ ; $V_G=20$ V; $t_{GP}=50$ $\mu$ s; $di_G/dt=2$ A/ $\mu$ s
THERMAL				
$T_{stg}$	Storage temperature	°C	-60 ÷ 125	
$T_j$	Operating junction temperature	°C	-60 ÷ 125	
MECHANICAL				
F	Mounting force	kN	40.0 ÷ 50.0	
a	Acceleration	m/s <sup>2</sup>	50 100	Device unclamped Device clamped

## CHARACTERISTICS

Symbols and parameters		Units	Values	Conditions
ON-STATE				
$V_{TM}$	Peak on-state voltage, max	V	1.55 2.15	$T_j=T_{j \max}$ ; $I_{TM}=4000$ A $T_j=25$ °C; $I_{TM}=6280$ A
$V_{T(TO)}$	On-state threshold voltage, max	V	1.40	$T_j=T_{j \max}$
$r_T$	On-state slope resistance, max	mΩ	0.080	$0.5 \pi I_{TAV} < I_T < 1.5 \pi I_{TAV}$
$I_H$	Holding current, max	mA	1000	$T_j=25$ °C; $V_D=12$ V; Gate open
BLOCKING				
$I_{DRM}, I_{RRM}$	Repetitive peak off-state and Repetitive peak reverse currents, max	mA	300	$T_j=T_{j \max}$ ; $V_D=V_{DRM}$ ; $V_R=V_{RRM}$
$(dv_D/dt)_{crit}$	Critical rate of rise of off-state voltage <sup>1)</sup> , min	V/ $\mu$ s	1000	$T_j=T_{j \max}$ ; $V_D=0.67V_{DRM}$ ; Gate open
TRIGGERING				
$V_{GT}$	Gate trigger direct voltage, max	V	5.00 3.00 2.00	$T_j=T_{j \min}$ $T_j=25$ °C $T_j=T_{j \max}$
$I_{GT}$	Gate trigger direct current, max	mA	500 300 200	$T_j=T_{j \min}$ $T_j=25$ °C $T_j=T_{j \max}$
$V_{GD}$	Gate non-trigger direct voltage, min	V	0.35	$T_j=T_{j \max}$ ; $V_D=0.67V_{DRM}$ ;
$I_{GD}$	Gate non-trigger direct current, min	mA	15.00	Direct gate current
SWITCHING				
$t_{gd}$	Delay time	$\mu$ s	2.00	$T_j=25$ °C; $V_D=0.4V_{DRM}$ ; $I_{TM}=I_{TAV}$ ; Gate pulse: $I_G=I_{FGM}$ ; $V_G=20$ V; $t_{GP}=50$ $\mu$ s; $di_G/dt=2$ A/ $\mu$ s
$t_q$	Turn-off time <sup>2)</sup> , max	$\mu$ s	10.0; 12.5; 16.0; 20.0	$dv_D/dt=50$ V/ $\mu$ s;
			12.5; 16.0; 20.0; 25.0	$dv_D/dt=200$ V/ $\mu$ s; $T_j=T_{j \max}$ ; $I_{TM}=I_{TAV}$ ; $di_R/dt=-10$ A/ $\mu$ s; $V_R=100$ V; $V_D=0.67V_{DRM}$
$Q_{rr}$	Total recovered charge(linear), max	$\mu$ C	220	$T_j=T_{j \max}$ ; $I_{TM}=2000$ A;
$t_{rr}$	Reverse recovery time, max	$\mu$ s	3.8	$di_R/dt=-50$ A/ $\mu$ s;
$I_{rrM}$	Peak reverse recovery current, max	A	115	$V_R=100$ V

THERMAL						
$R_{thjc}$	Thermal resistance, junction to case, max		$^{\circ}\text{C}/\text{W}$	0.0085	Direct current	Double side cooled
$R_{thjc-A}$				0.0187		Anode side cooled
$R_{thjc-K}$				0.0153		Cathode side cooled
$R_{thck}$	Thermal resistance, case to heatsink, max		$^{\circ}\text{C}/\text{W}$	0.0020	Direct current	

## MECHANICAL

w	Weight, typ	g	1500				
$D_s$	Surface creepage distance	mm (inch)	36.60 (1.441)				
$D_a$	Air strike distance	mm (inch)	16.20 (0.638)				

## NOTES

<sup>1)</sup> Critical rate of rise of off-state voltage

Symbol of group	A2
$(dv_D/dt)_{crit}, \text{V}/\mu\text{s}$	1000

<sup>2)</sup> Turn-off time ( $dv_D/dt=50 \text{ V}/\mu\text{s}$ )

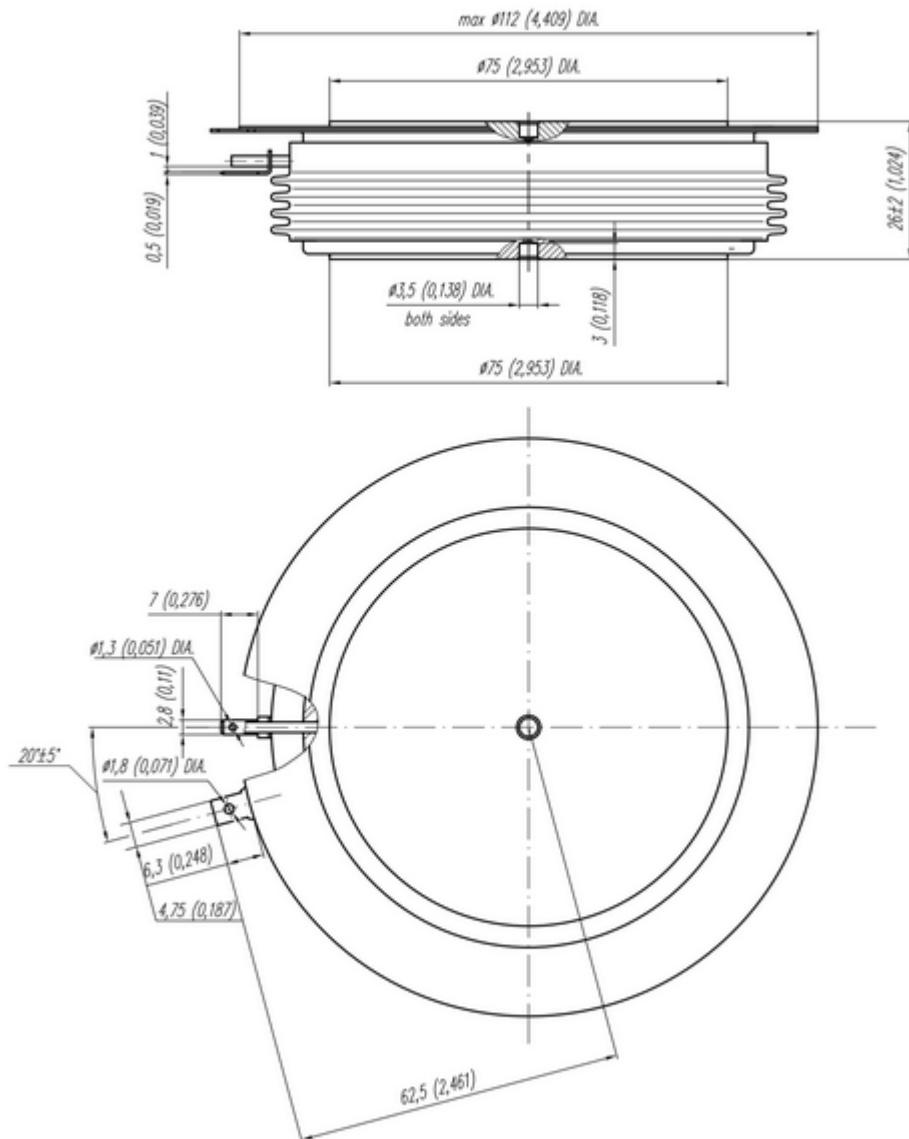
Symbol of group	A4	X3	T3	P3
$t_q, \mu\text{s}$	10.0	12.5	16.0	20.0

## PART NUMBERING GUIDE

TFI	573	2000	12	A2	A4	N
1	2	3	4	5	6	7
1. TFI — Fast Thyristor						
TFIS — Fast Thyristor with Distributed Amplified Gate						
2. Design version						
3. Mean on-state current, A						
4. Voltage code						
5. Critical rate of rise of off-state voltage						
6. Group of turn-off time ( $dv_D/dt=50 \text{ V}/\mu\text{s}$ )						
7. Ambient conditions: N – normal; T – tropical						

## OVERALL DIMENSIONS

Package type: T.F2



All dimensions in millimeters (inches)

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### On-state characteristic model (see Fig. 1).

Analytical function for On-state characteristic:

$$V_T = A + B \cdot i_T + C \cdot \ln(i_T + 1) + D \cdot \sqrt{i_T}$$

	Coefficients	
	$T_j = 25^\circ\text{C}$	$T_j = T_{j\max}$
<b>A</b>	1.886396	1.150214
<b>B</b>	0.019465	0.062607
<b>C</b>	0.018317	0.024464
<b>D</b>	0.041506	0.055434

### Transient thermal impedance junction to case $Z_{thjc}$ model (see Fig. 2).

Analytical function for Transient thermal impedance junction to case  $Z_{thjc}$  for DC:

$$Z_{thjc} = \sum_{i=1}^n R_i \left( 1 - e^{-\frac{t}{\tau_i}} \right)$$

Where  $i = 1$  to  $n$ ,  $n$  is the number of terms in the series.

$t$  = Duration of heating pulse in seconds.

$Z_{thjc}$  = Thermal resistance at time  $t$ .

$R_i$  = Amplitude of  $p_{th}$  term.

$\tau_i$  = Time constant of  $r_{th}$  term.

DC Double side cooled

i	1	2	3	4	5	6
<b><math>R_i</math> K/W</b>	0.0003136	0.003279	0.0001485	0.0007865	0.0002694	0.003703
<b><math>\tau_i</math> s</b>	1.181	0.06771	0.003331	0.145	0.0004353	0.9499

DC Anode side cooled

i	1	2	3	4	5	6
<b><math>R_i</math> K/W</b>	0.01013	0.004062	0.0009701	0.00306	0.000148	0.0002685
<b><math>\tau_i</math> s</b>	9.747	1.058	0.1302	0.06675	0.003276	0.0004342

DC Cathode side cooled

i	1	2	3	4	5	6
<b><math>R_i</math> K/W</b>	0.006619	0.004032	0.0008219	0.003231	0.000147	0.0002716
<b><math>\tau_i</math> s</b>	9.745	1.026	0.143	0.06778	0.00342	0.0004396

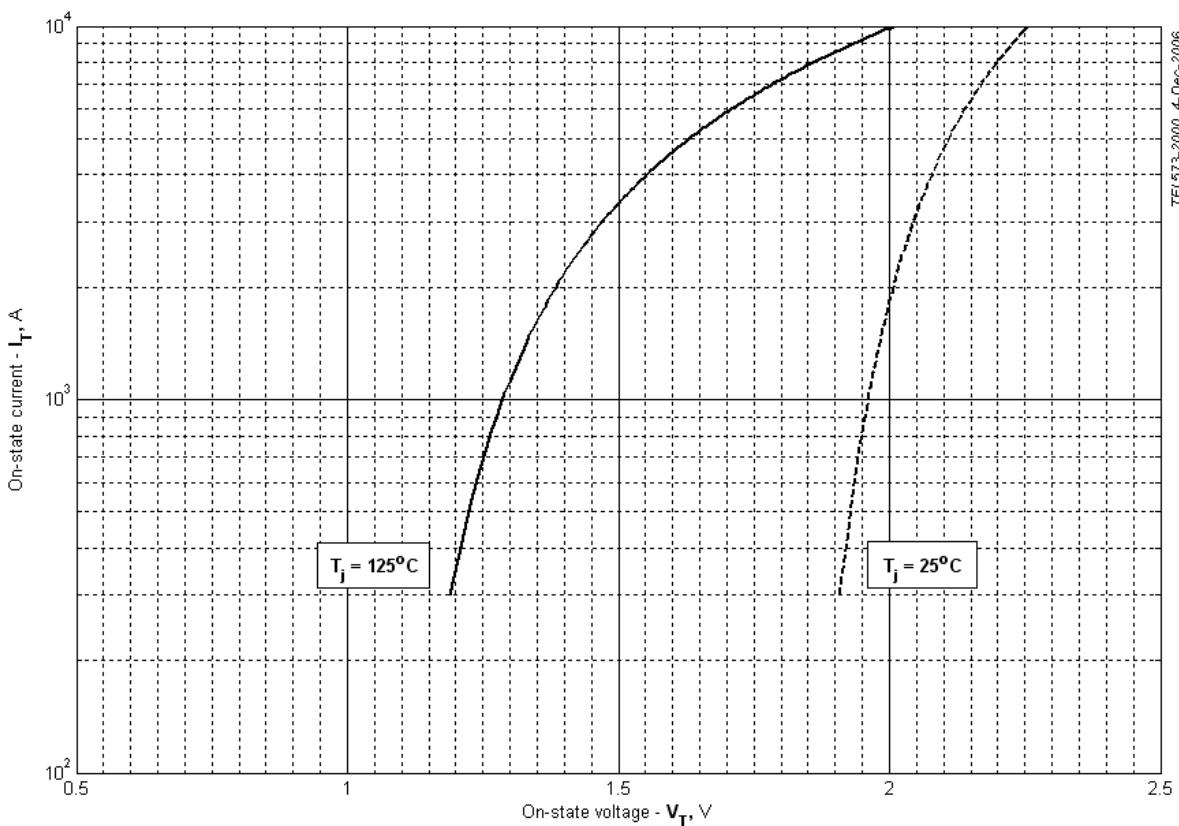


Fig 1 – On-state characteristics of Limit device

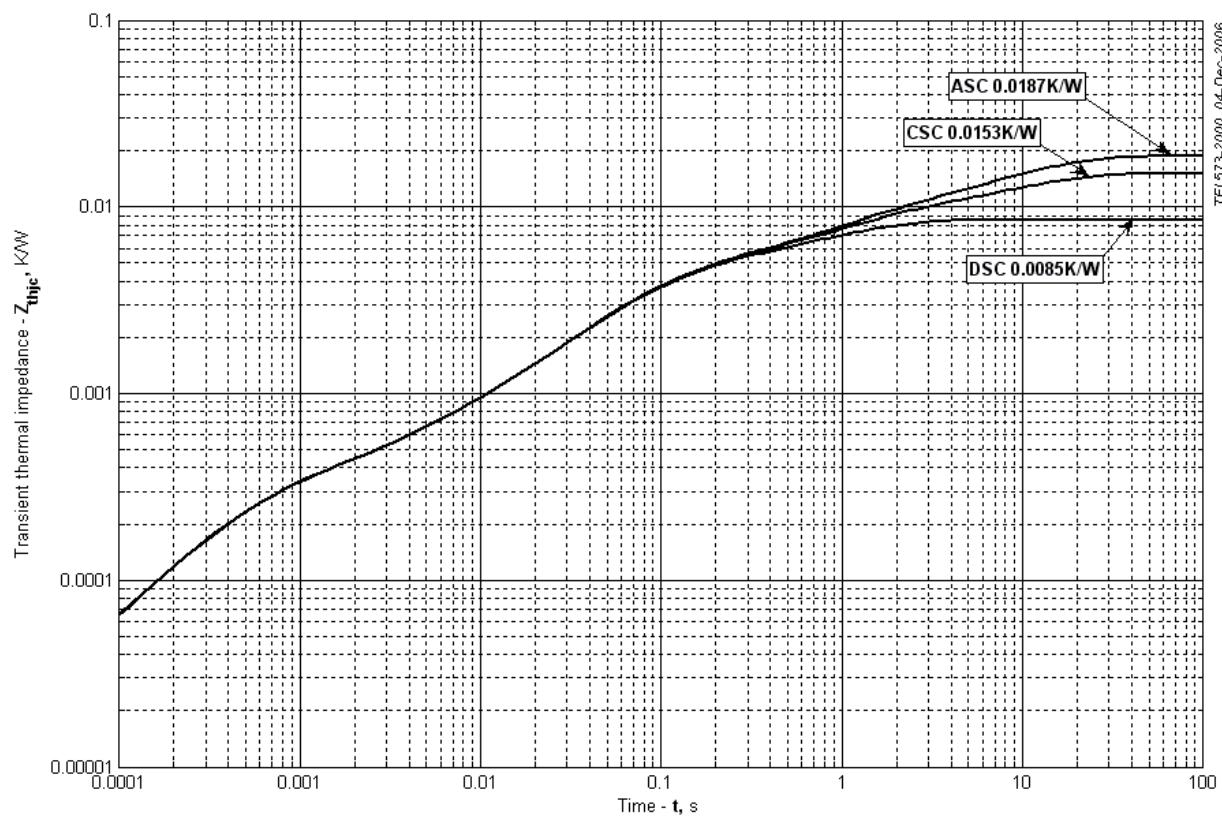


Fig 2 – Transient thermal impedance

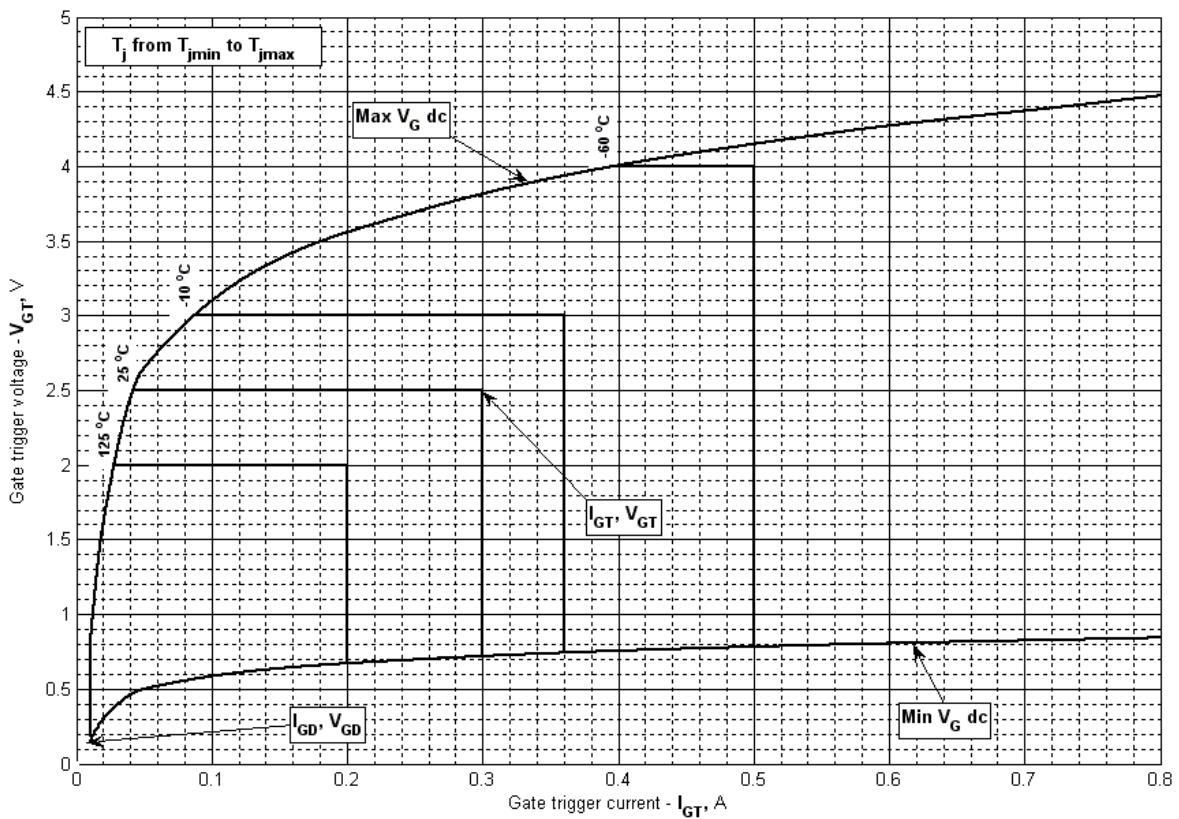


Fig 3 – Gate characteristics – Trigger limits

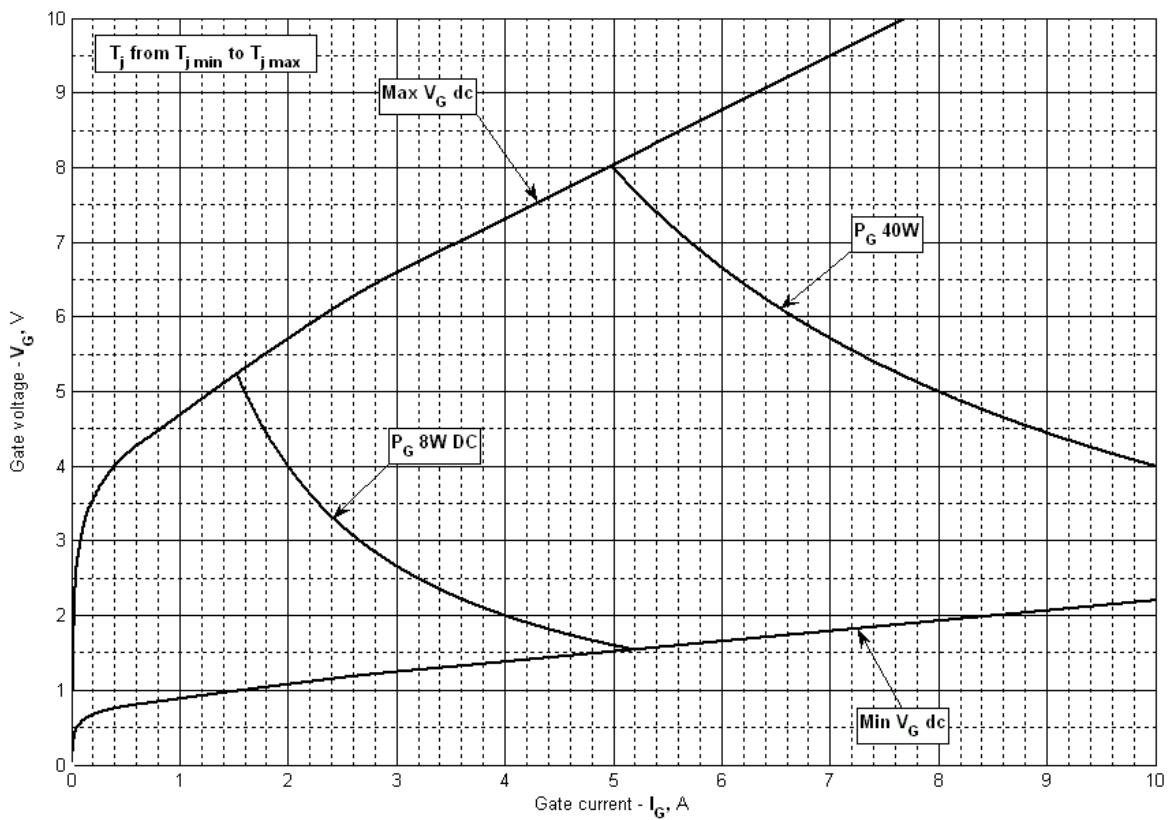


Fig 4 - Gate characteristics –Power curves

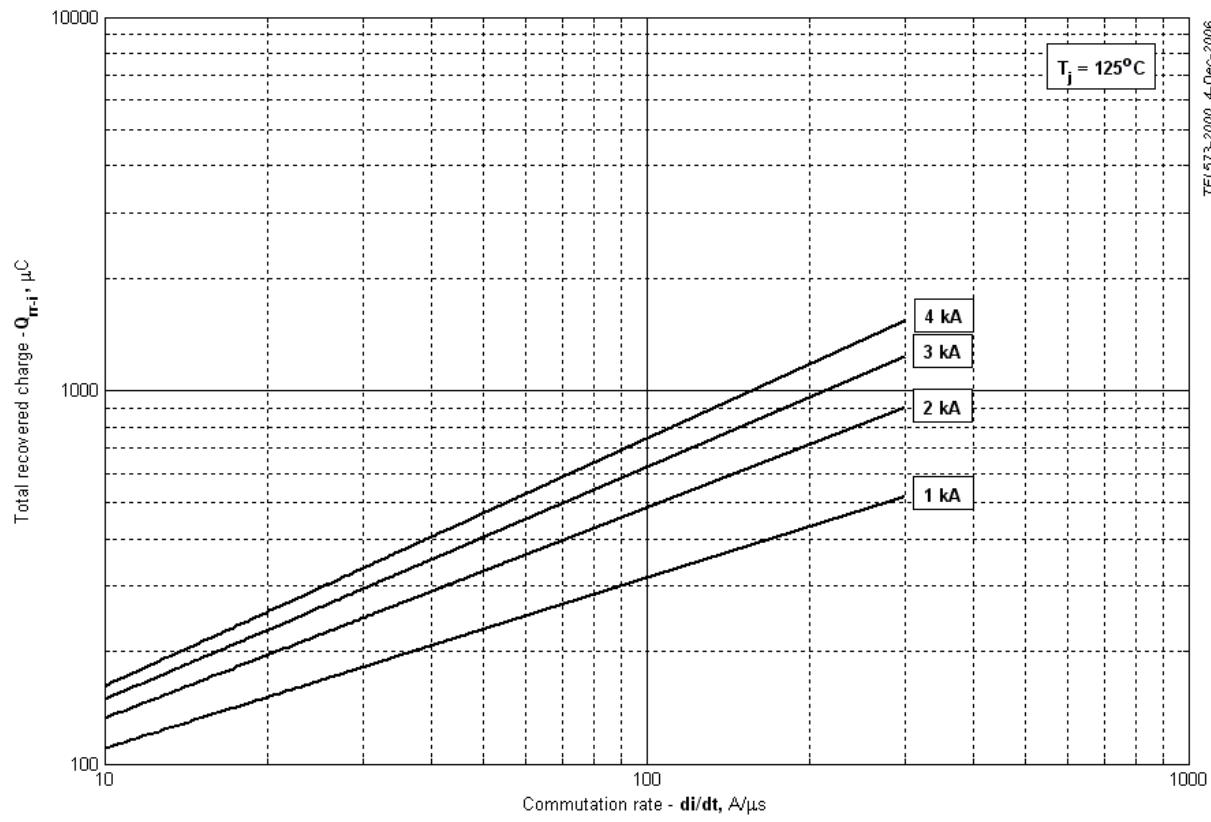


Fig 5 – Total recovered charge,  $Q_{rr-i}$  (integral)

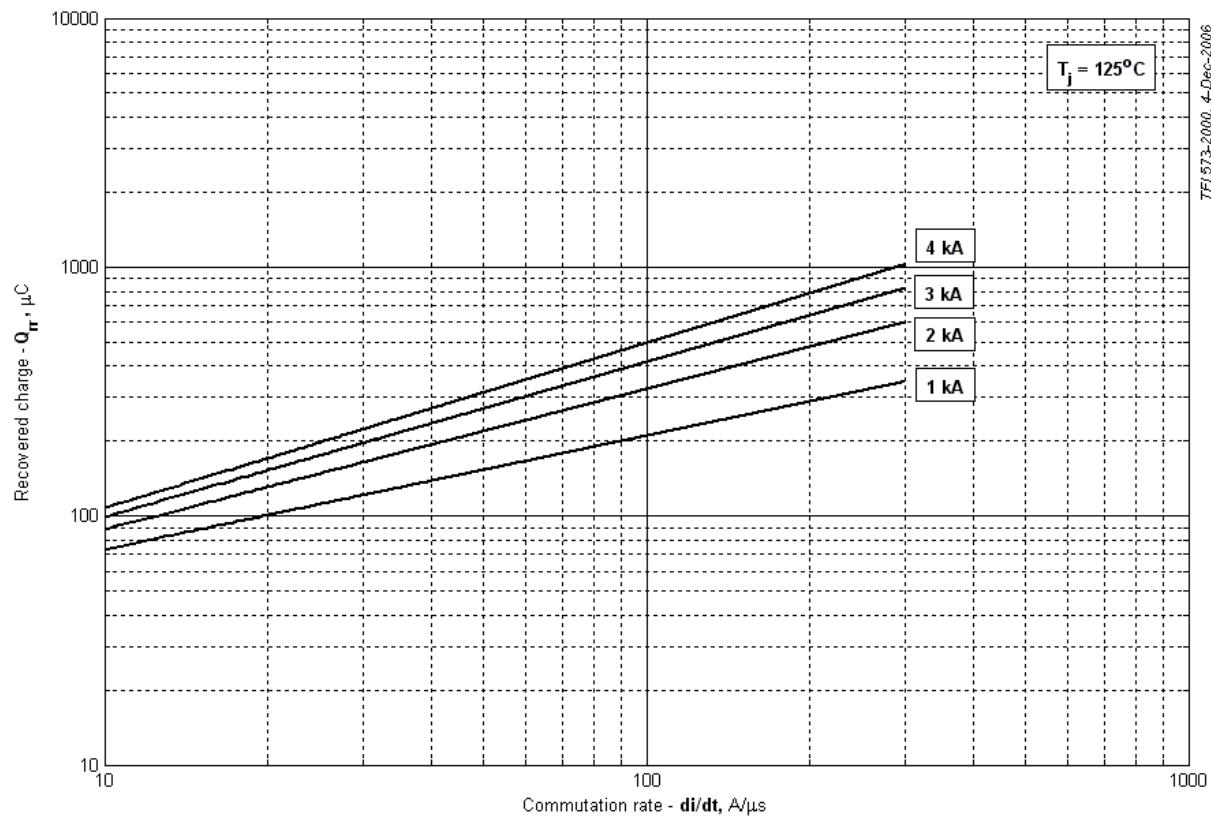


Fig 6 - Recovered charge,  $Q_{rr}$  (linear)

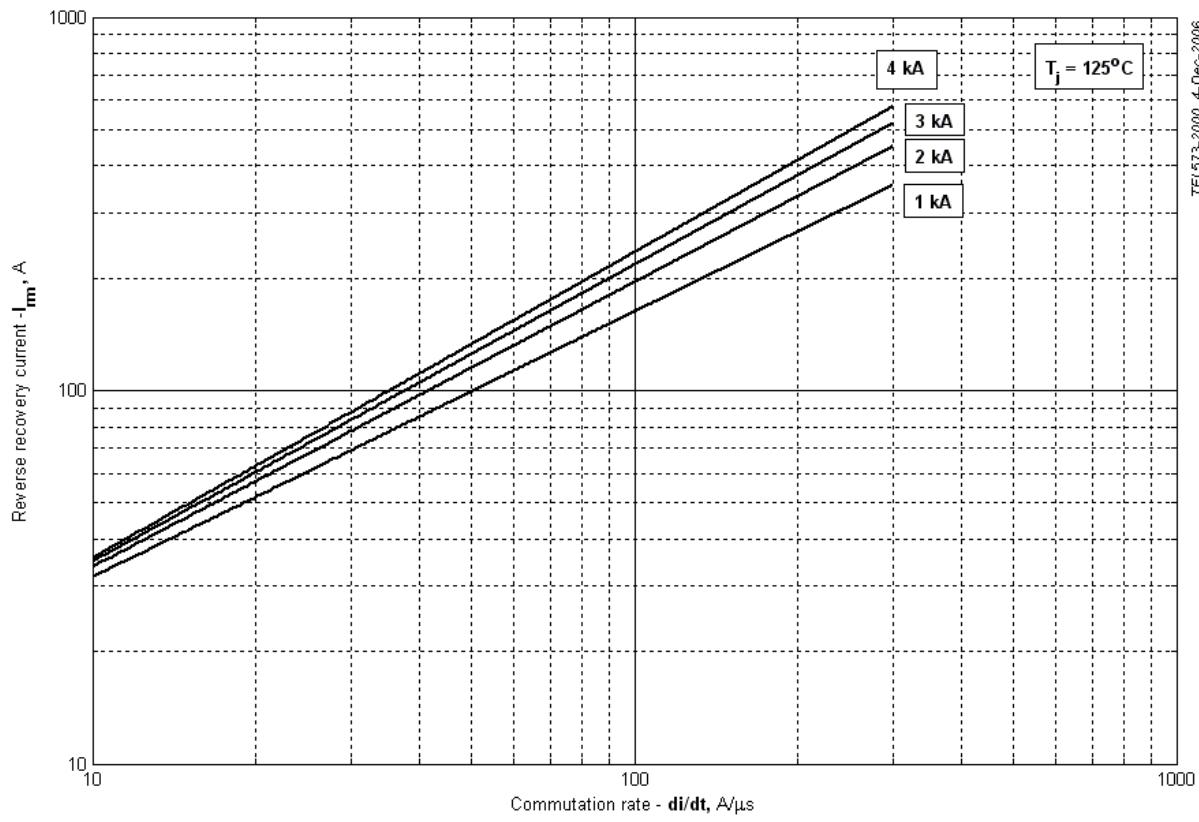


Fig 7 – Peak reverse recovery current,  $I_{rm}$

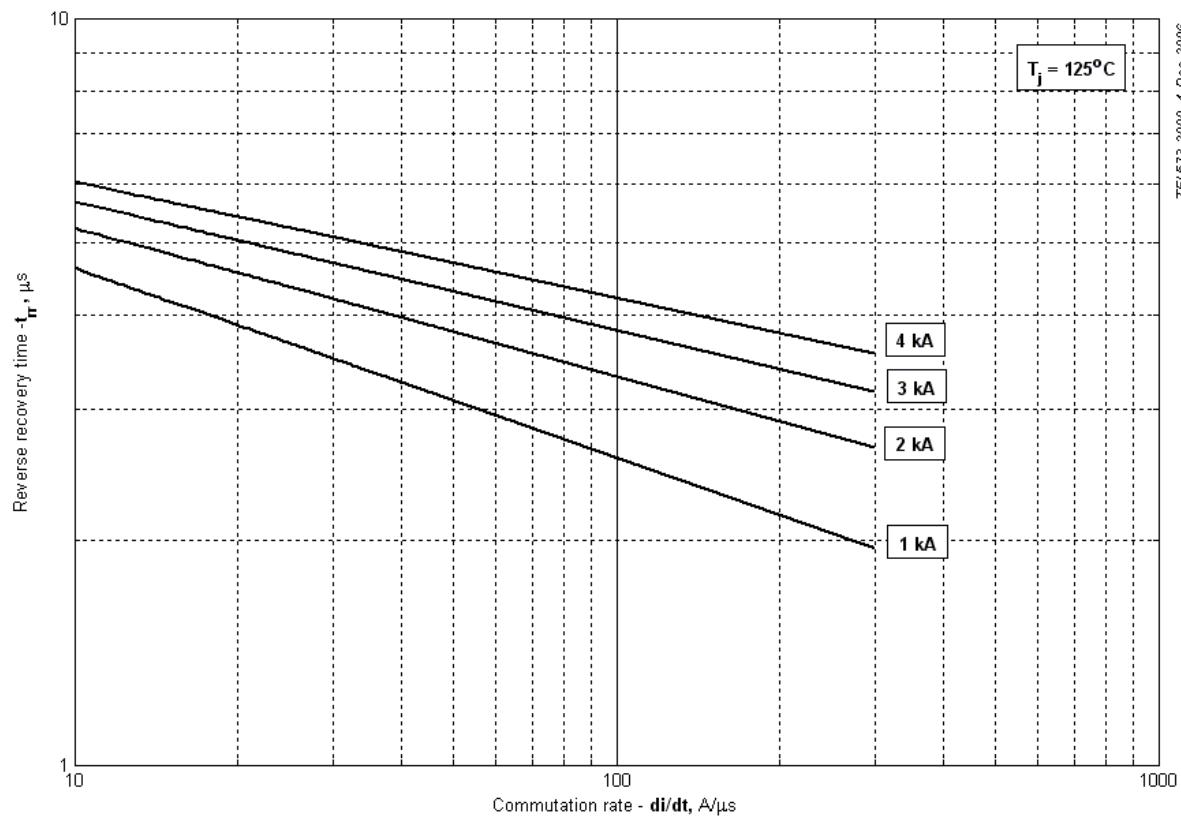


Fig 8 – Typical recovery time,  $t_{rr}$  (linear)

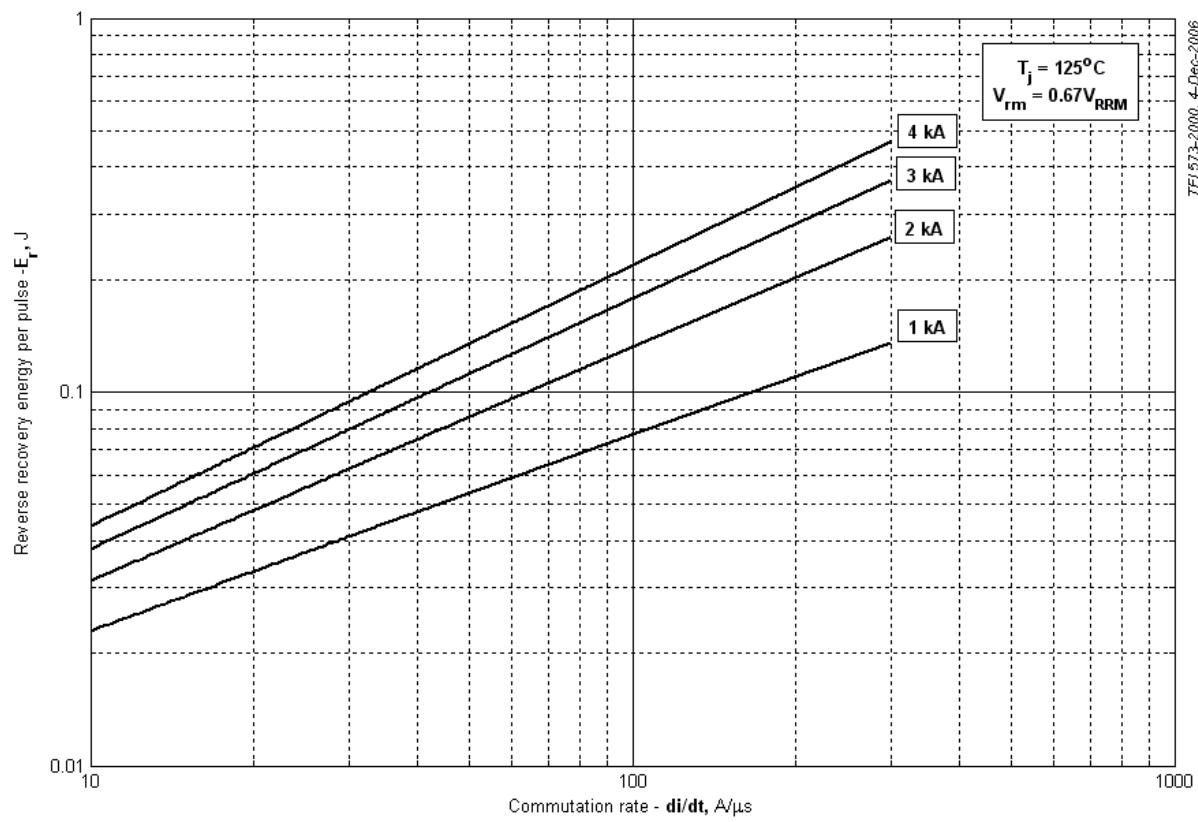


Fig 9 – Reverse recovery energy per pulse

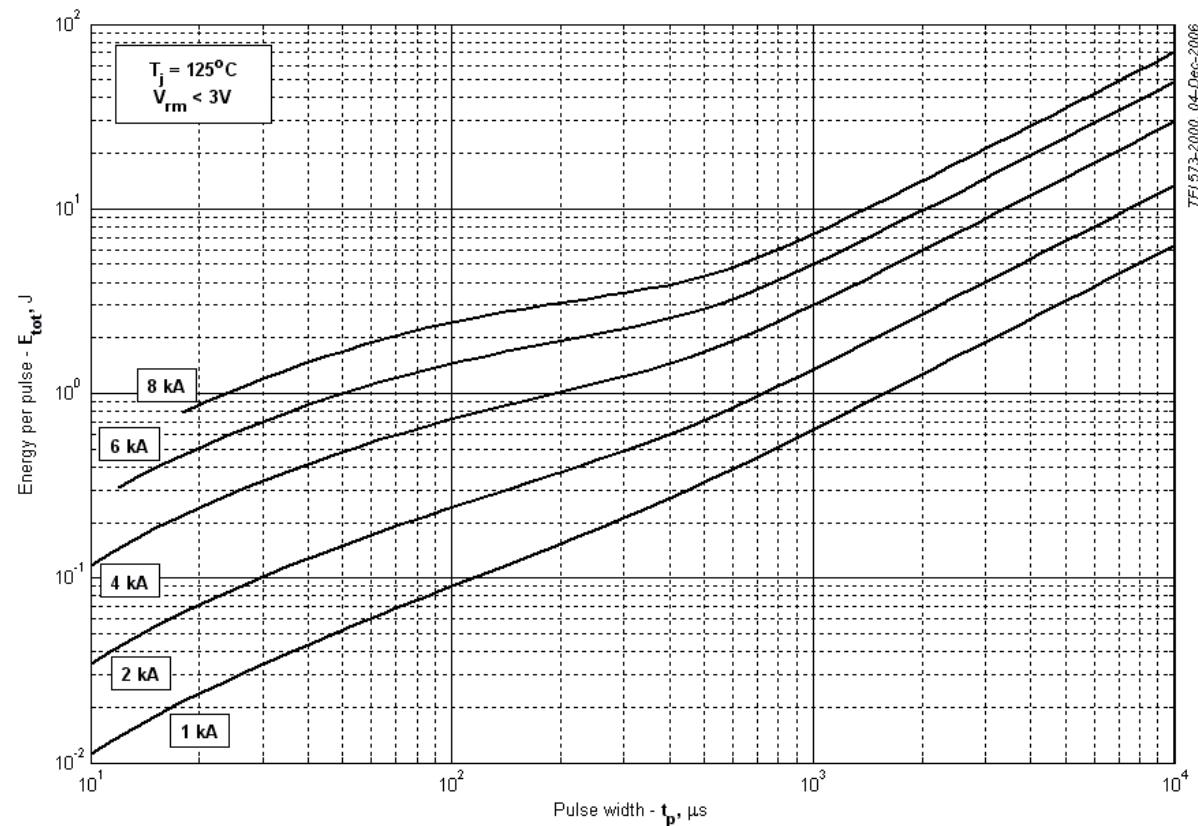


Fig 10 – Sine wave energy per pulse

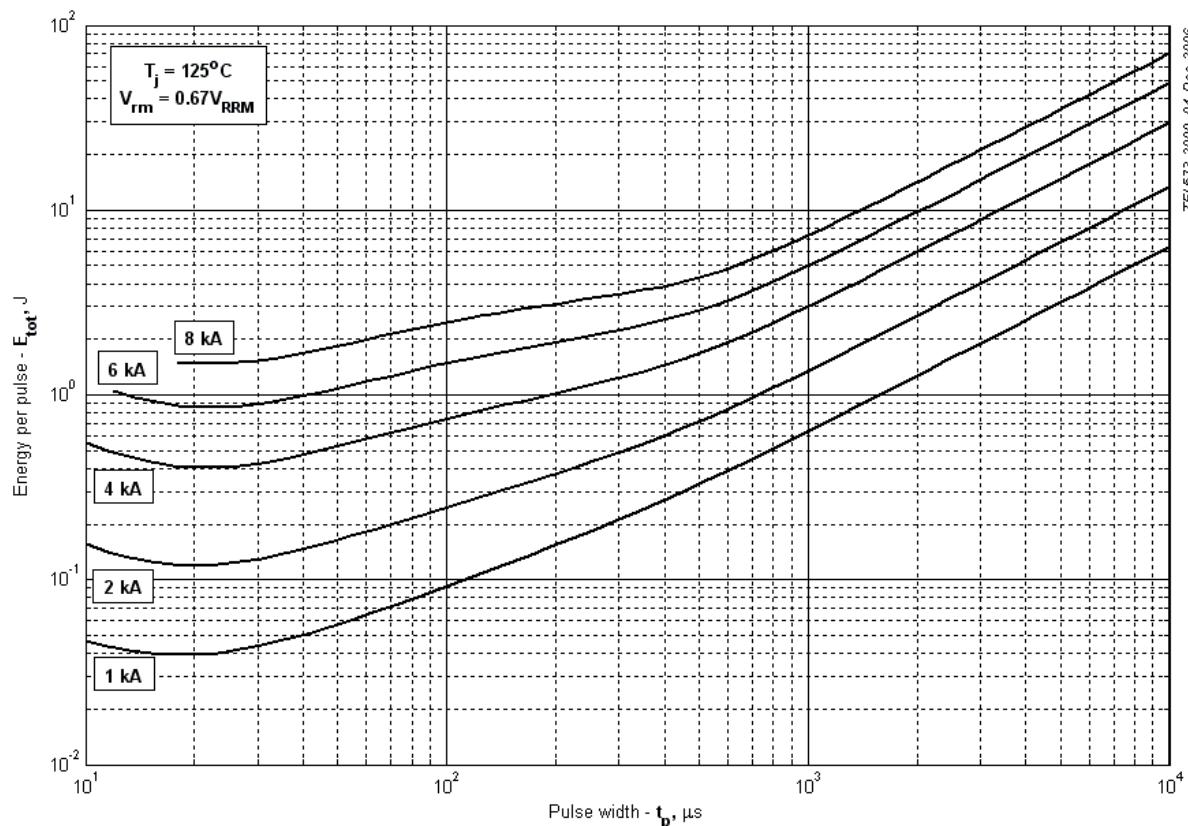


Fig 11 – Sine wave energy per pulse

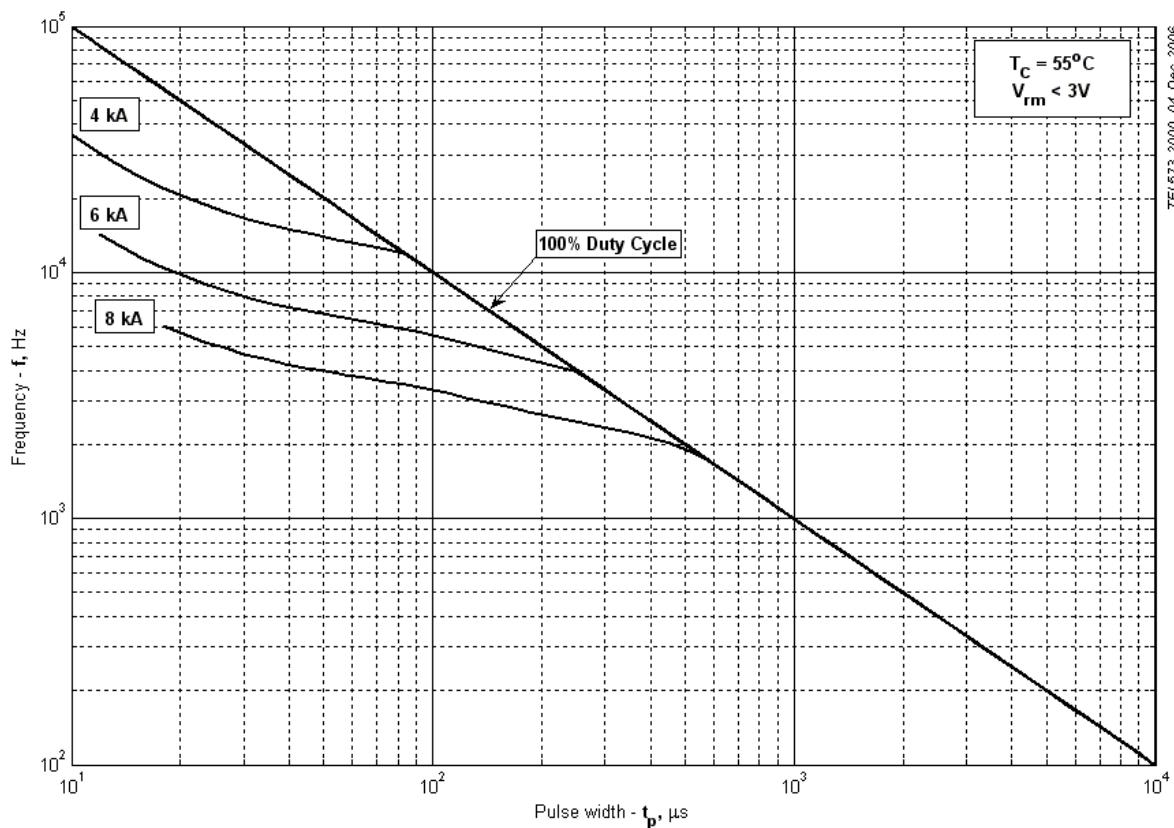


Fig 12 – Sine wave frequency ratings

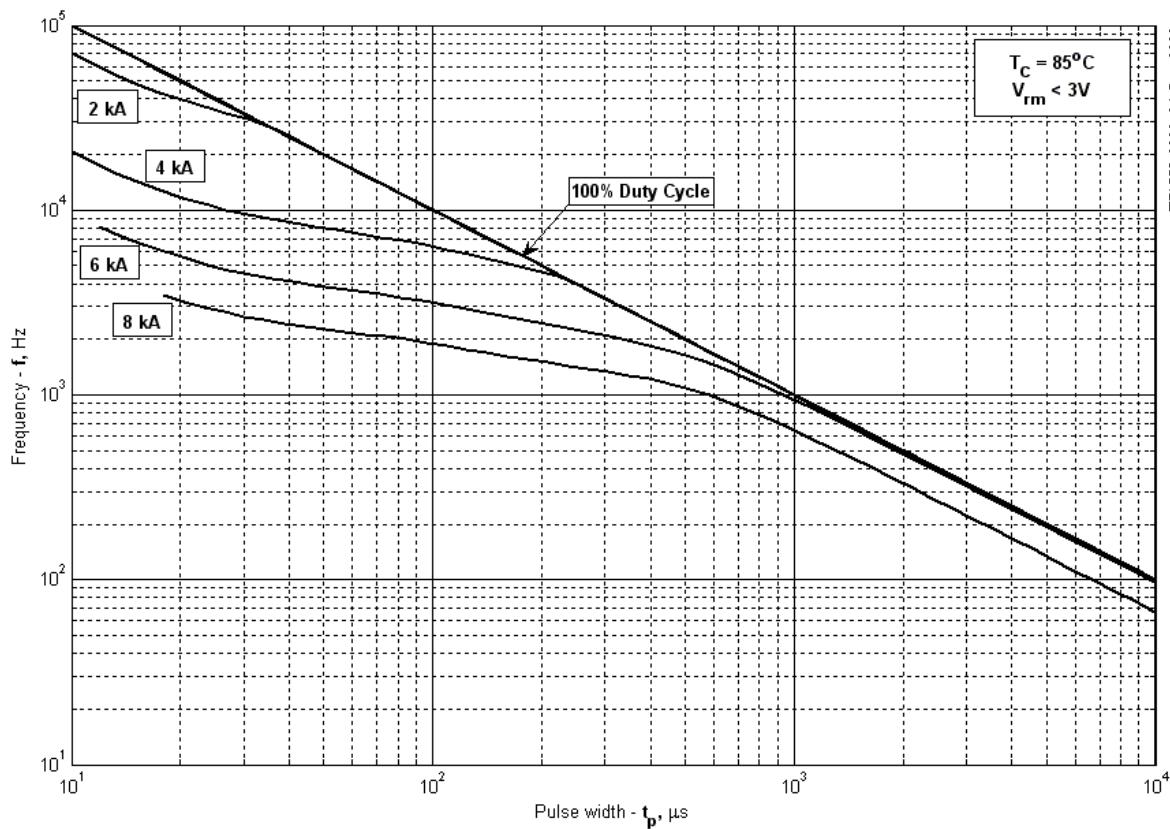


Fig 13 – Sine wave frequency ratings

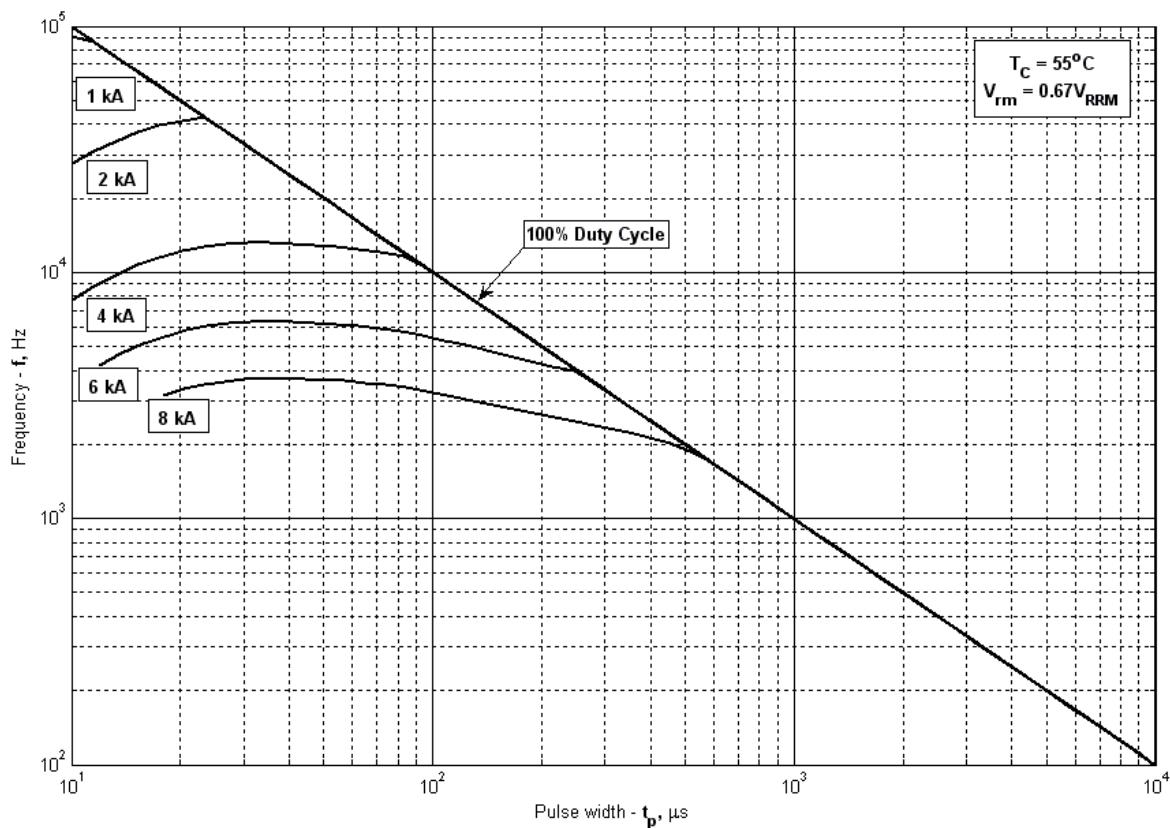
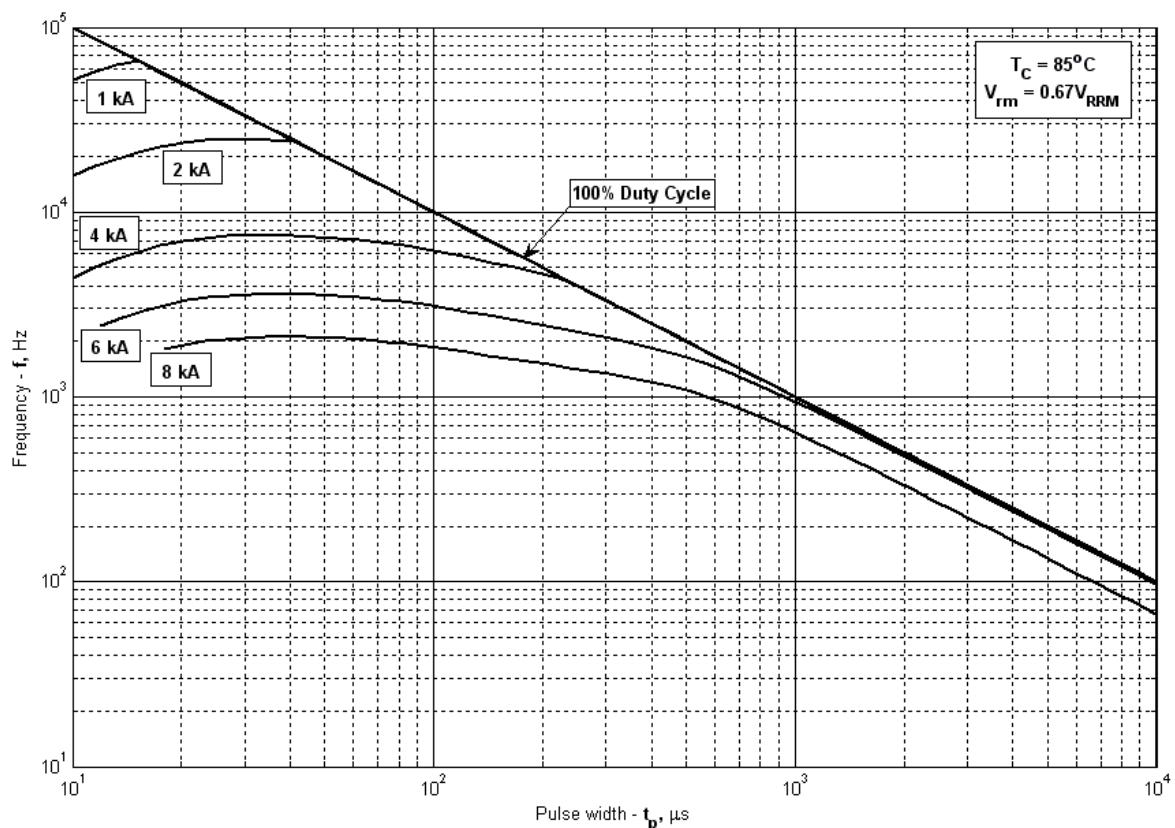
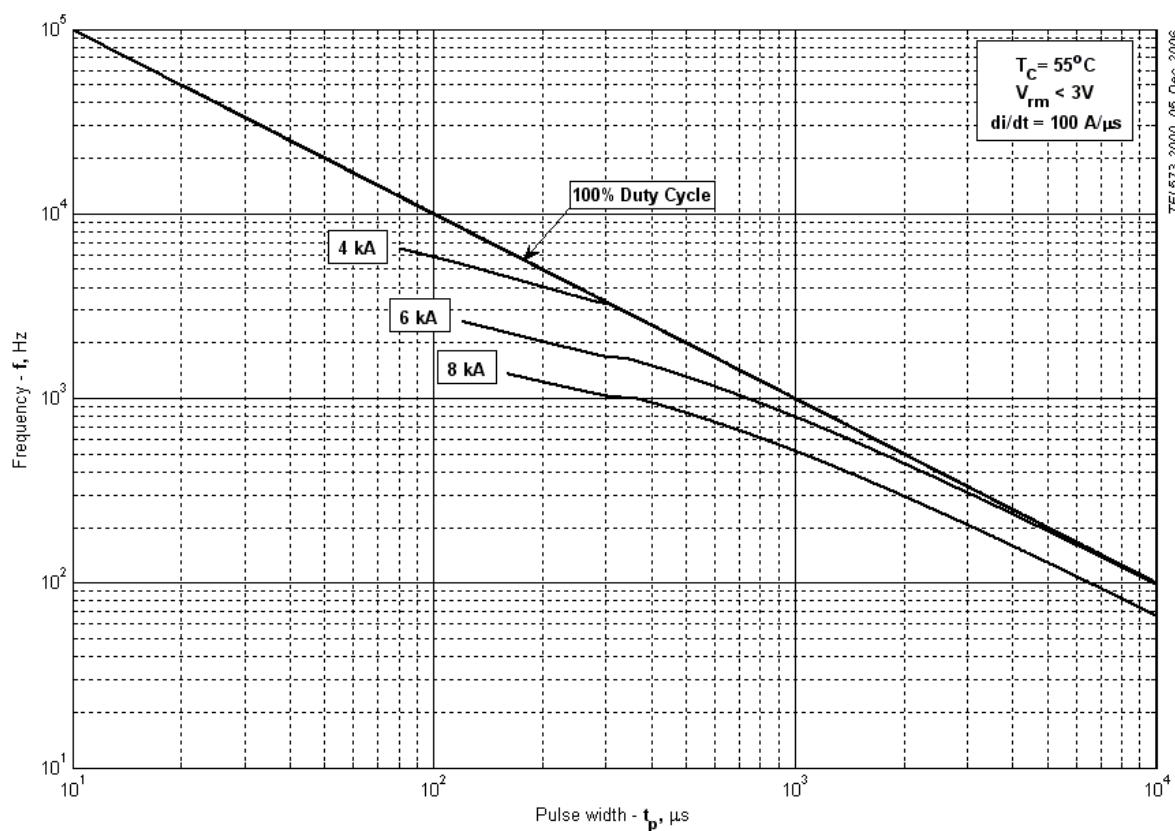


Fig 14 – Sine wave frequency ratings



TFI573-2000, 04-Dec-2006

Fig 15 – Sine wave frequency ratings



TFI573-2000, 05-Dec-2006

Fig 16 – Square wave frequency ratings

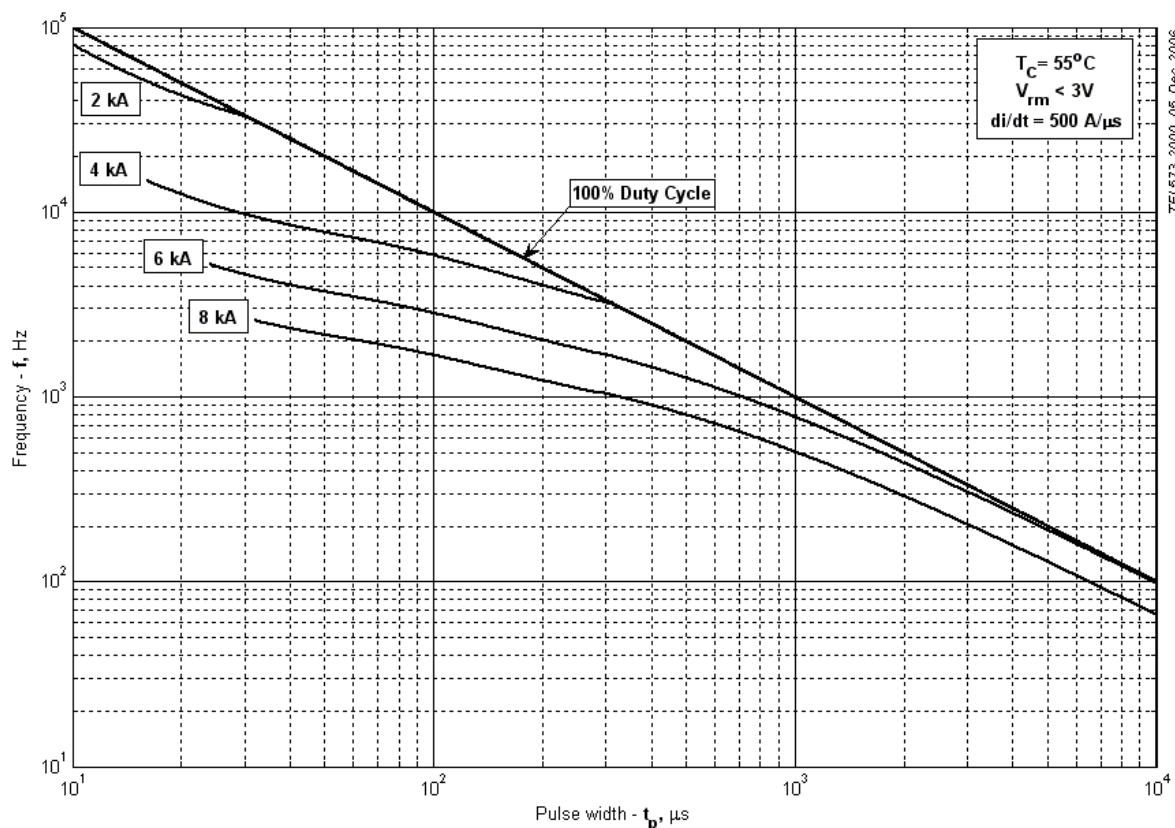


Fig 17 – Square wave frequency ratings

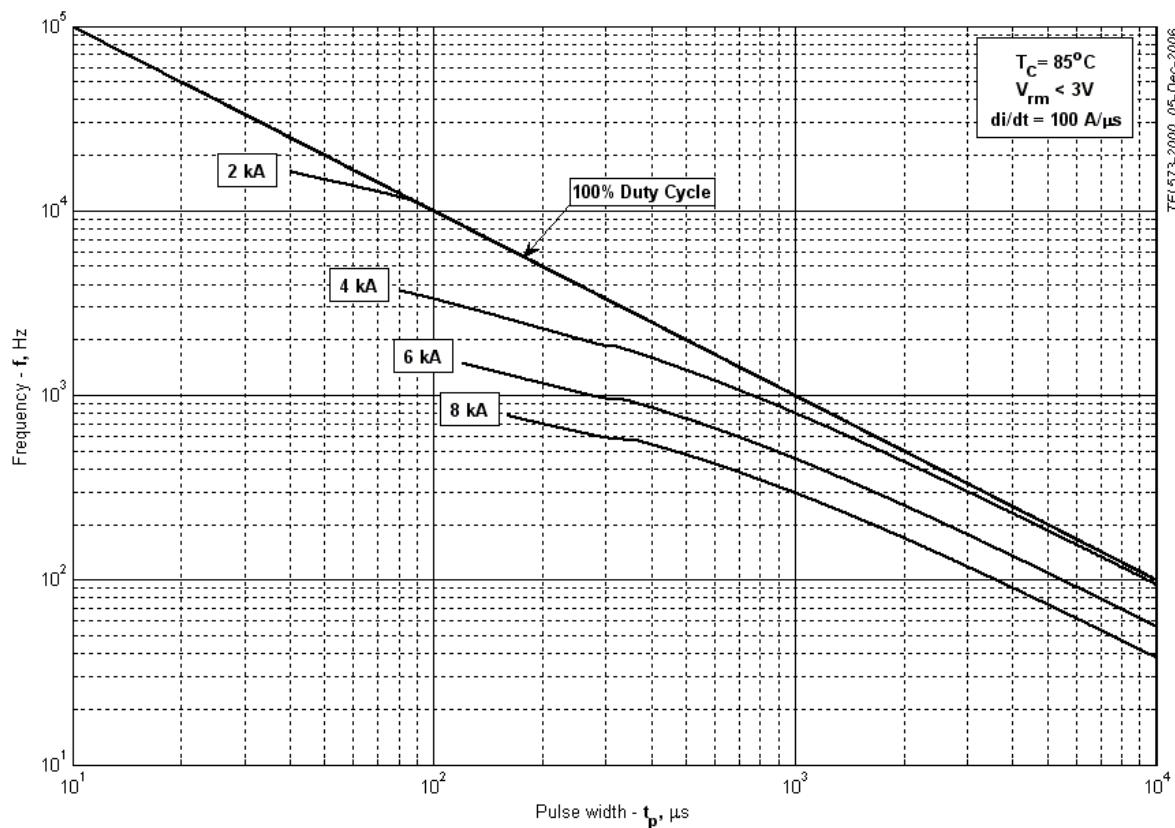


Fig 18 – Square wave frequency ratings

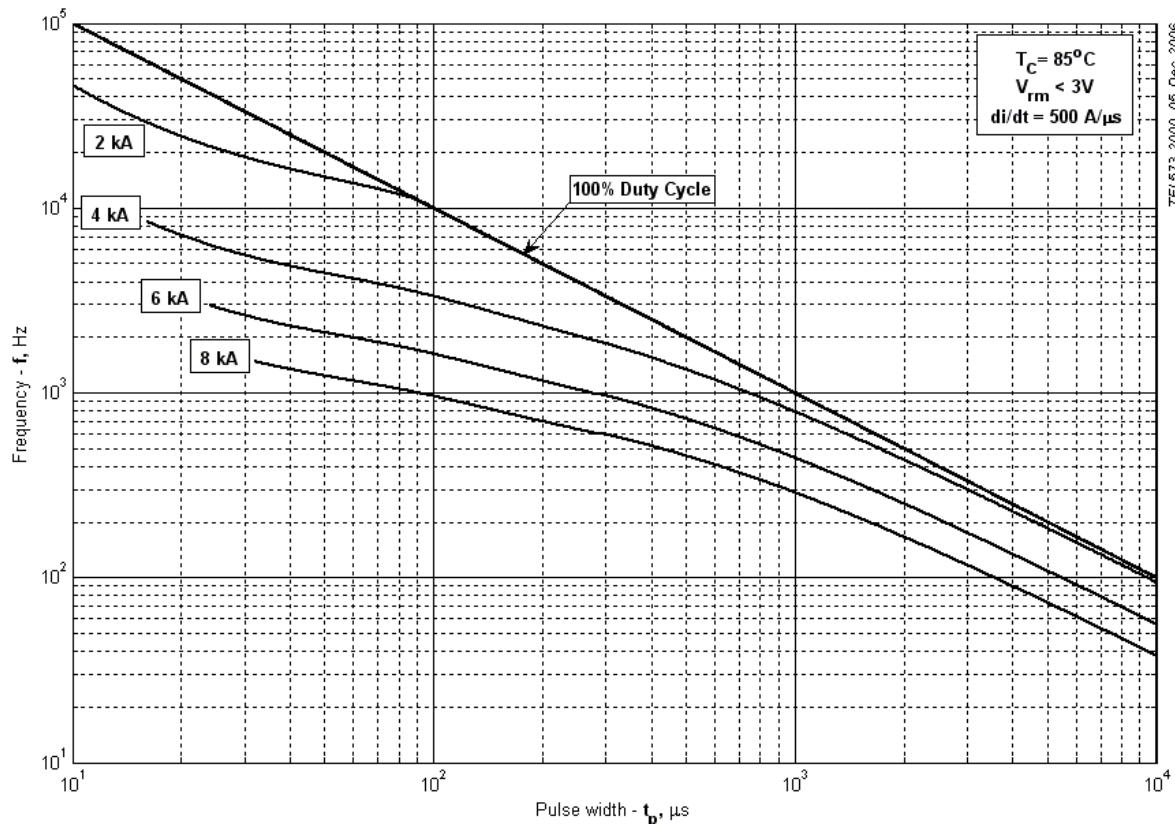


Fig 19 – Square wave frequency ratings

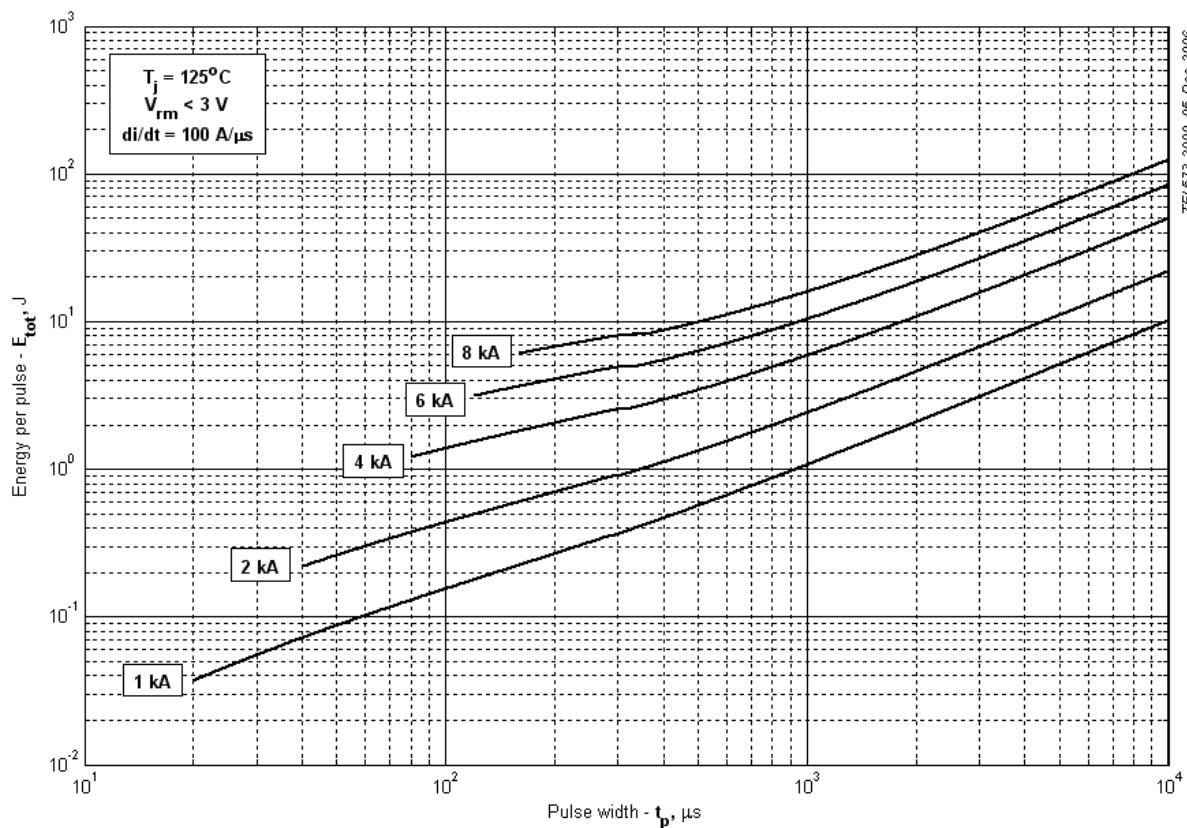


Fig 20 – Square wave energy per pulse

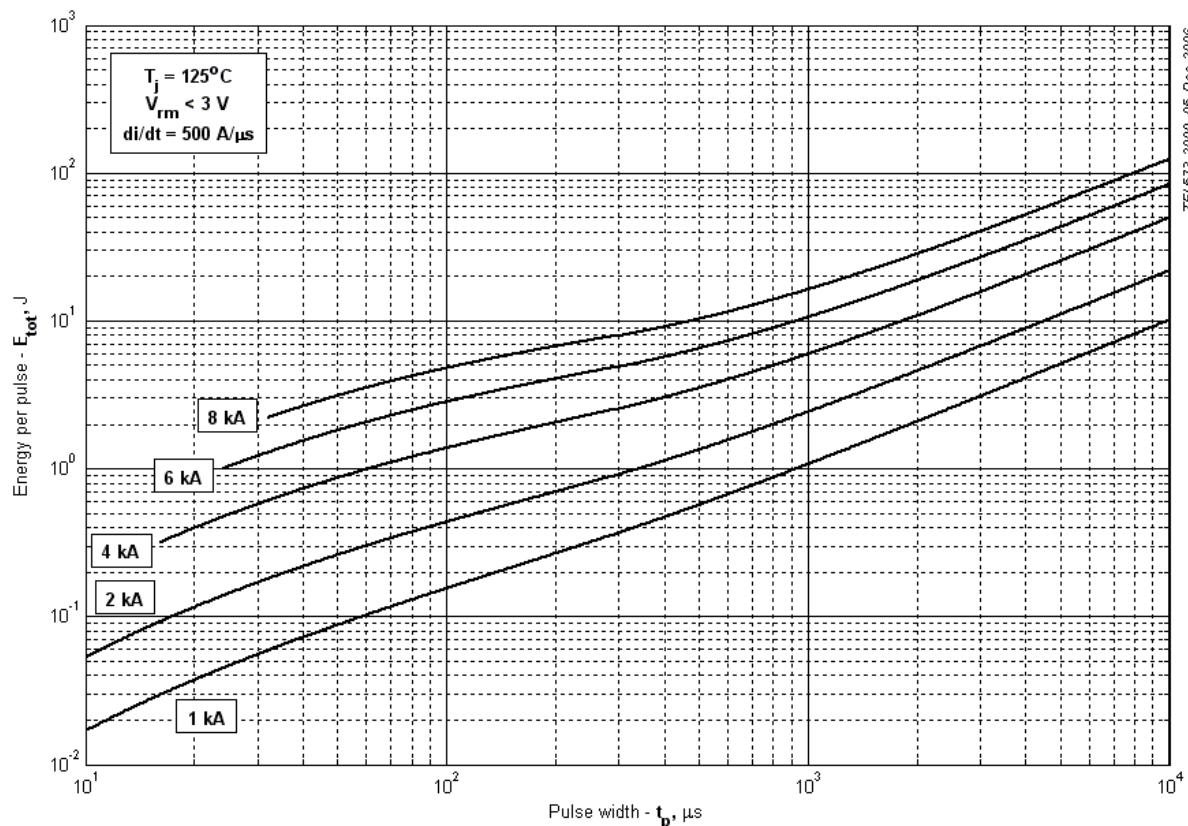


Fig 21 – Square wave energy per pulse

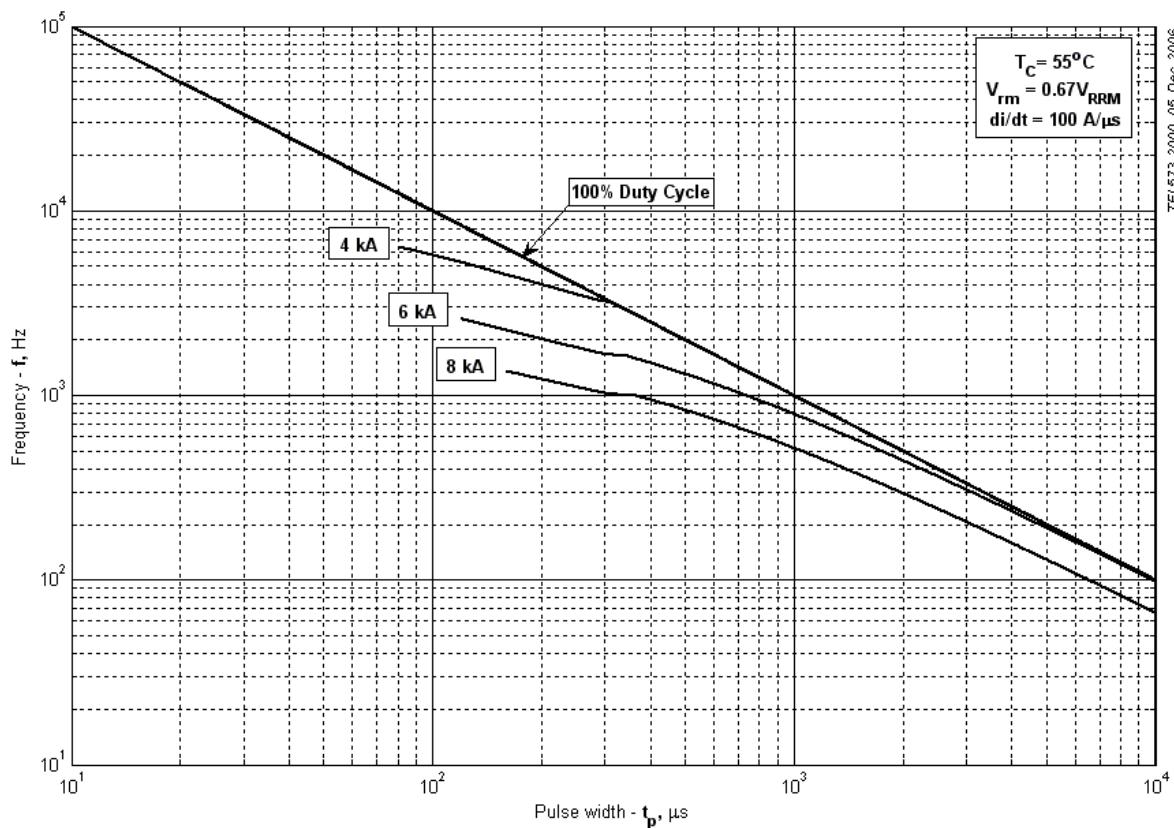


Fig 22 – Square wave frequency ratings

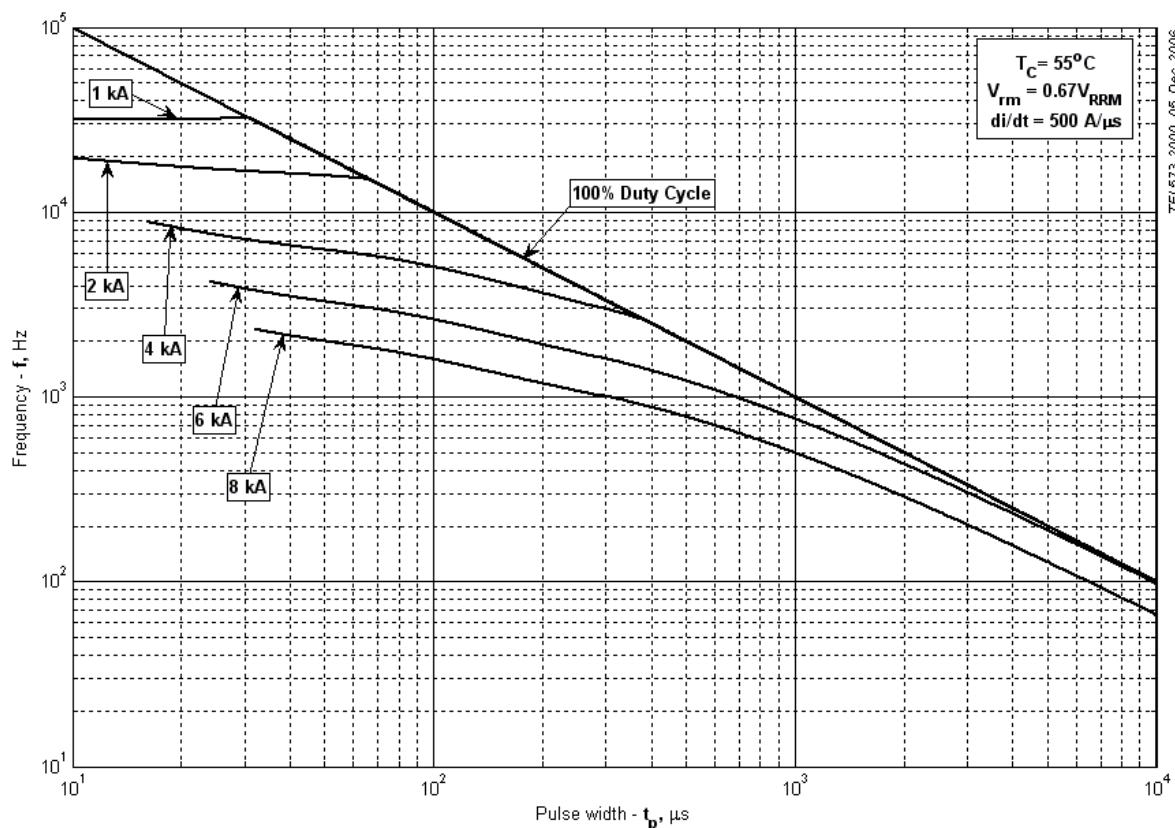


Fig 23 – Square wave frequency ratings

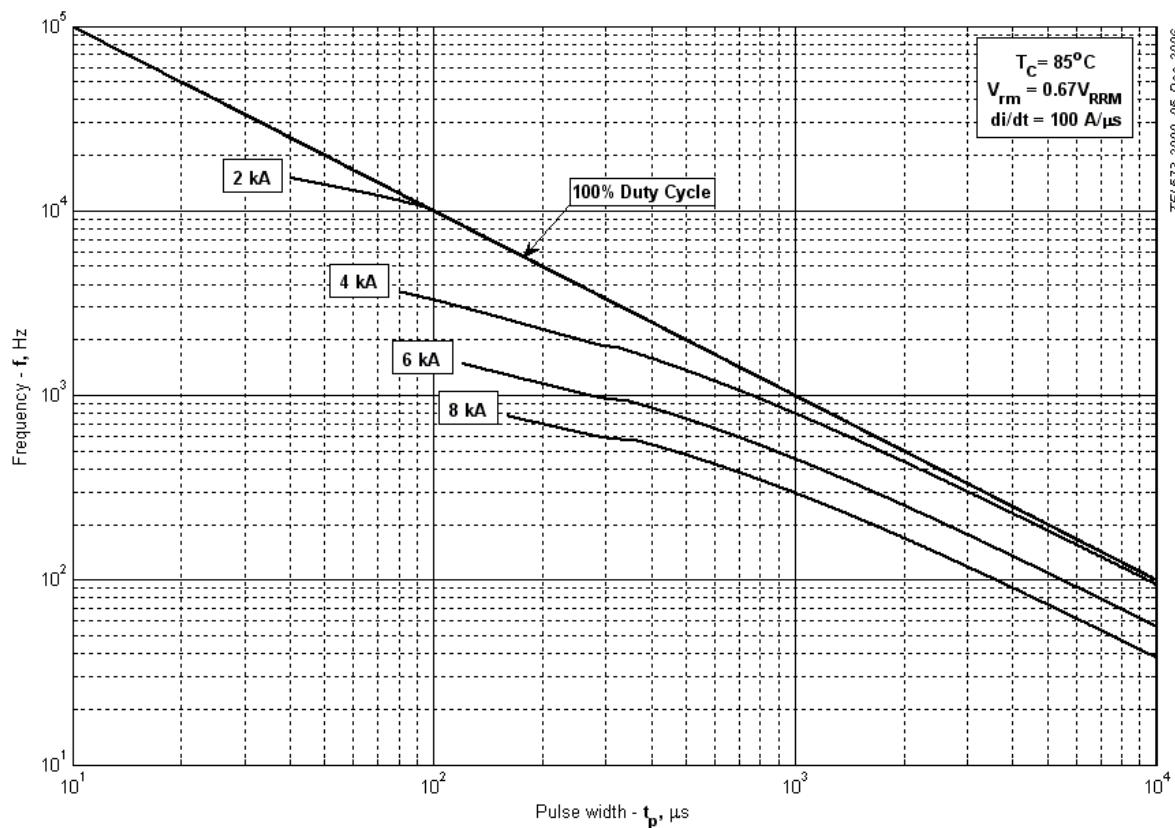


Fig 24 – Square wave frequency ratings

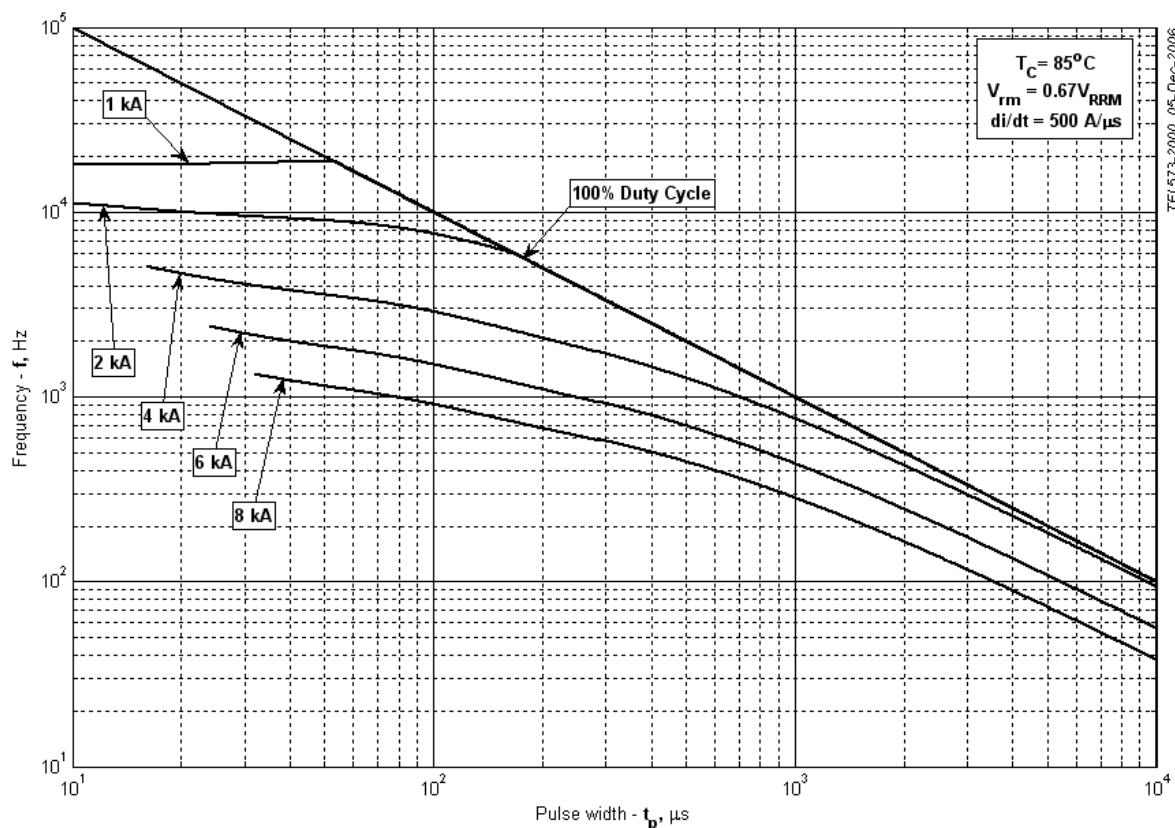


Fig 25 – Square wave frequency ratings

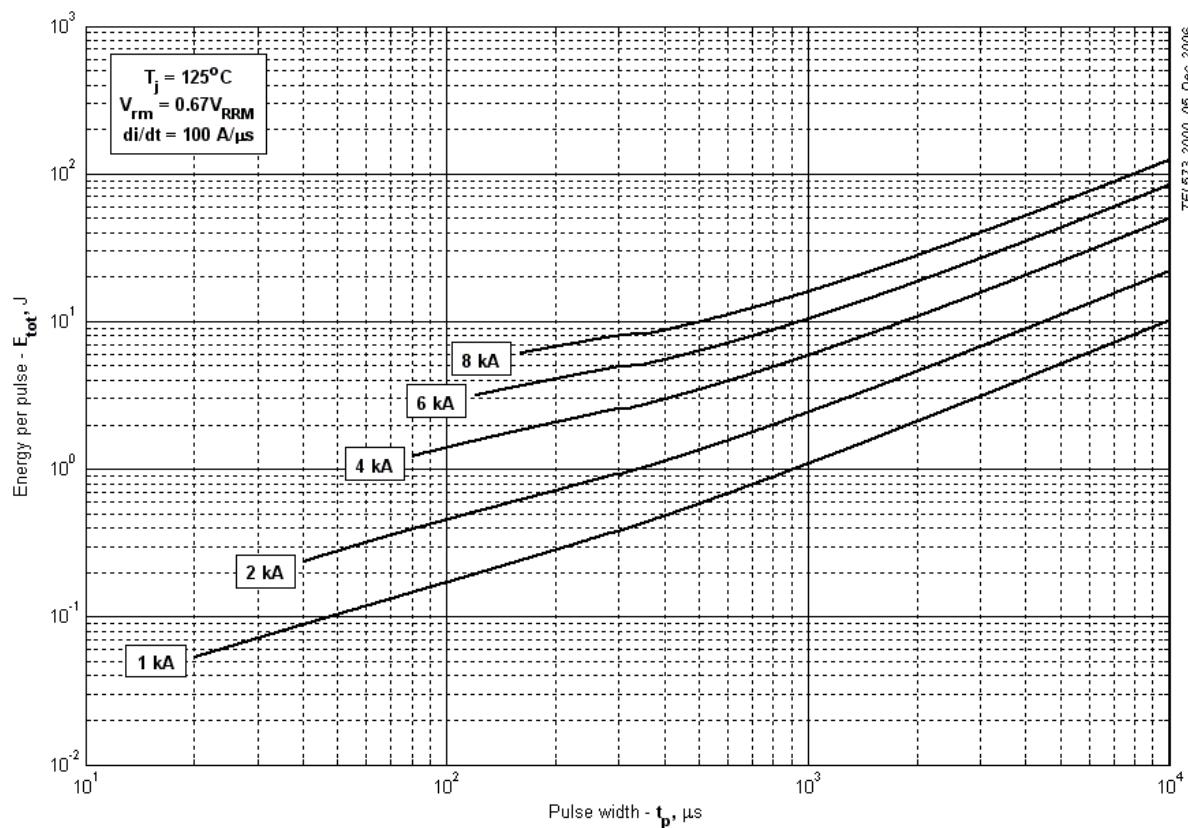


Fig 26 – Square wave energy per pulse

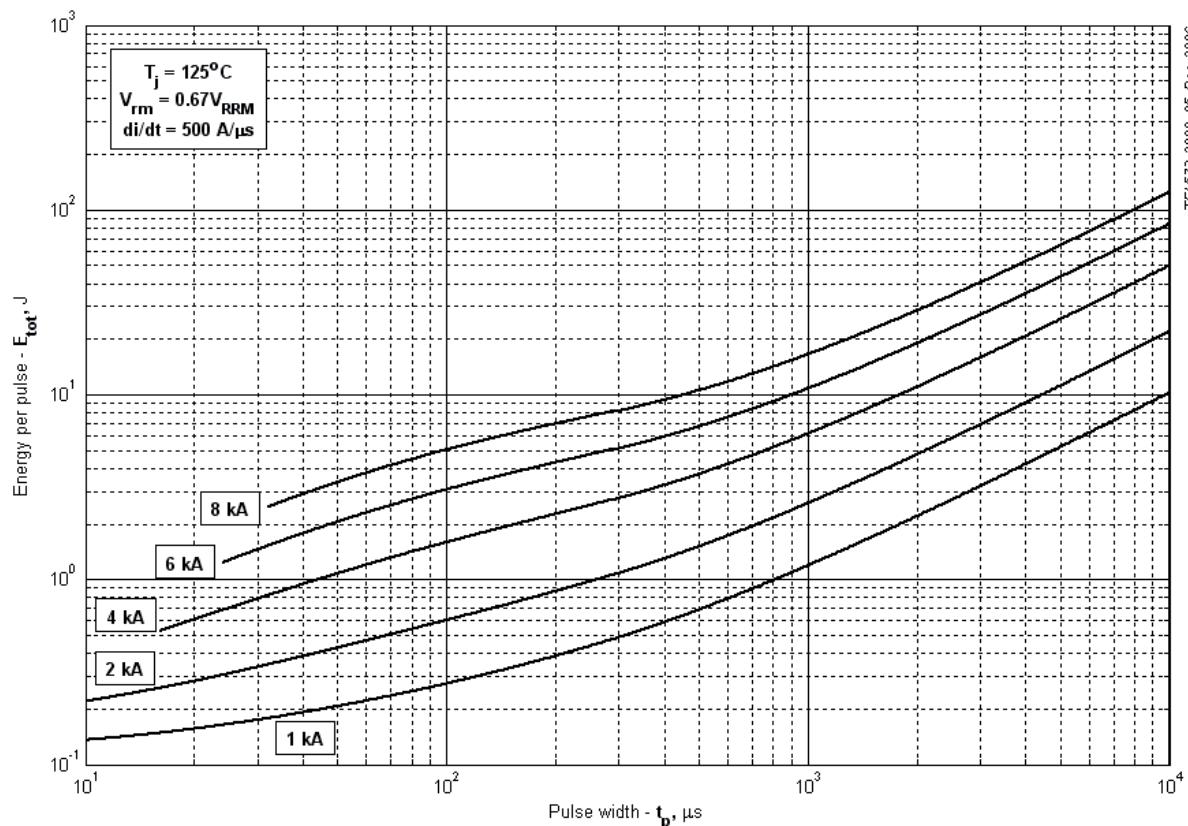


Fig 27 – Square wave energy per pulse

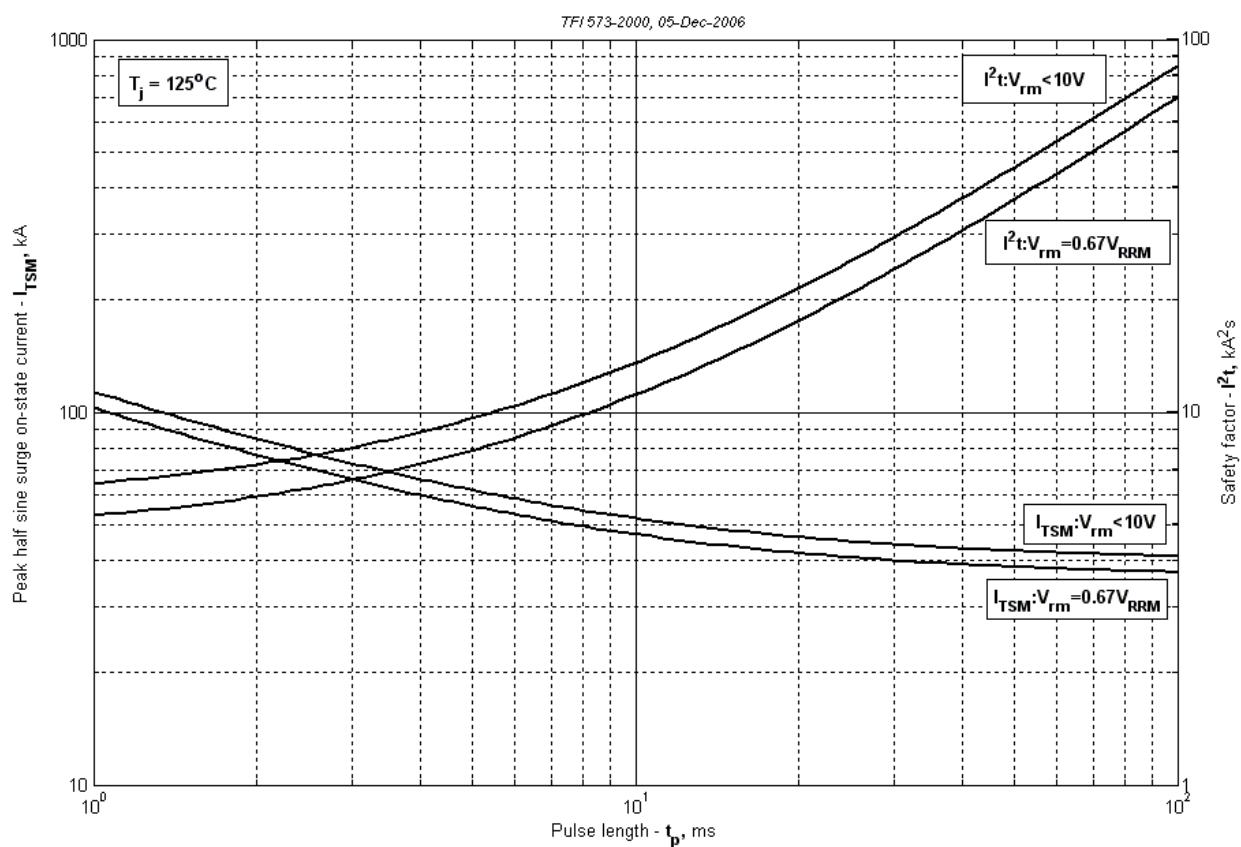


Fig 29 – Maximum surge and  $I^2t$  ratings

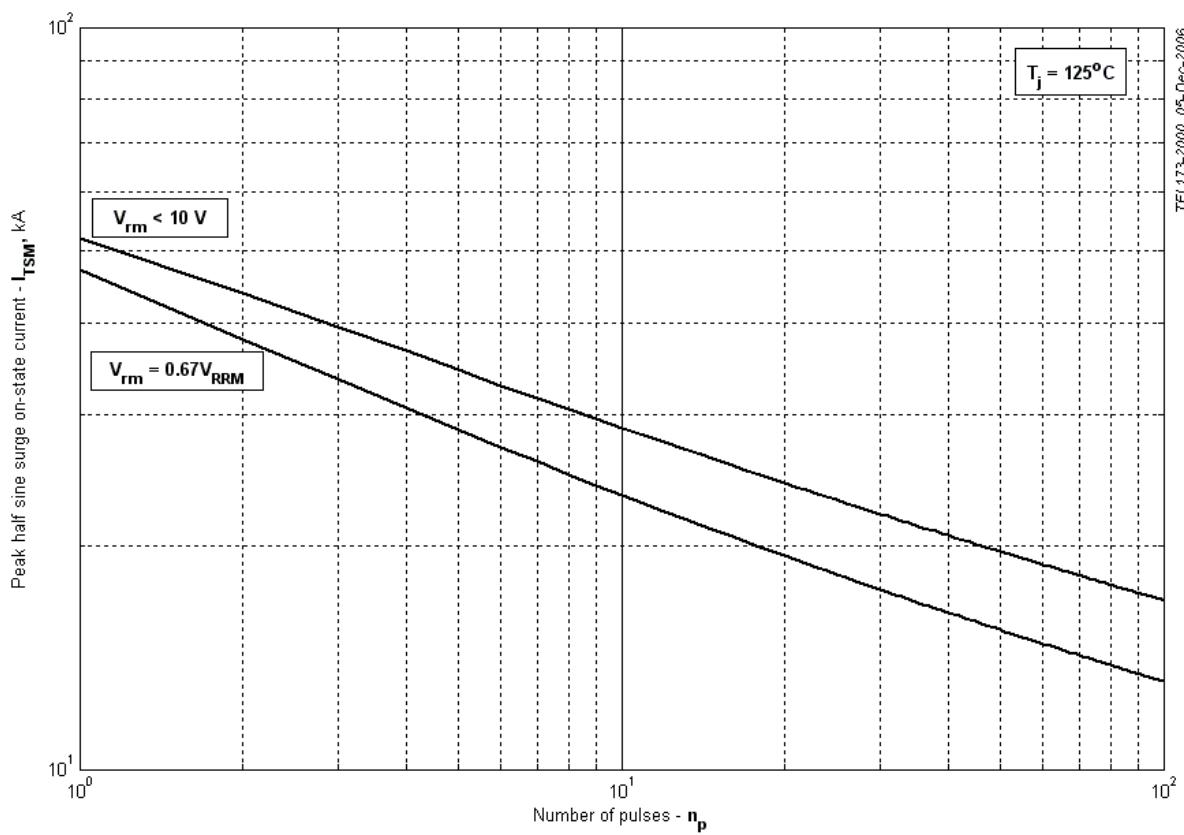


Fig 30 – Maximum surge ratings